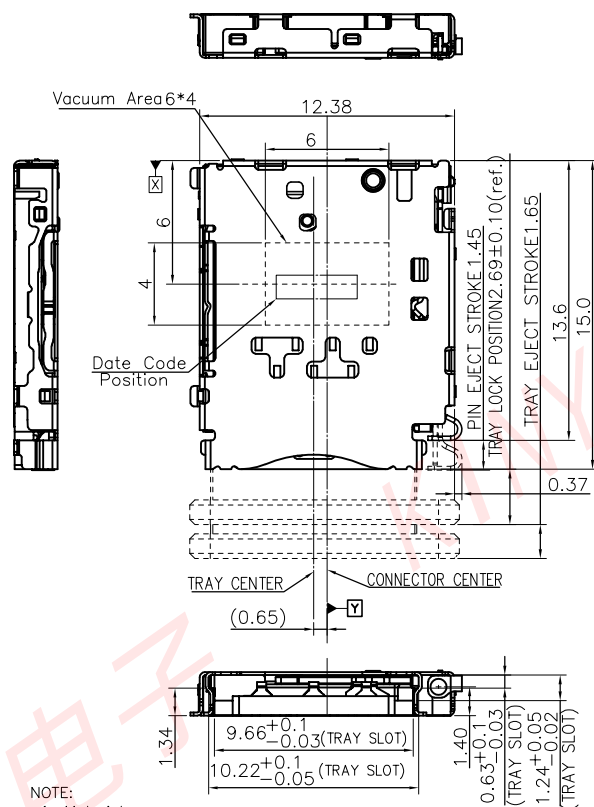
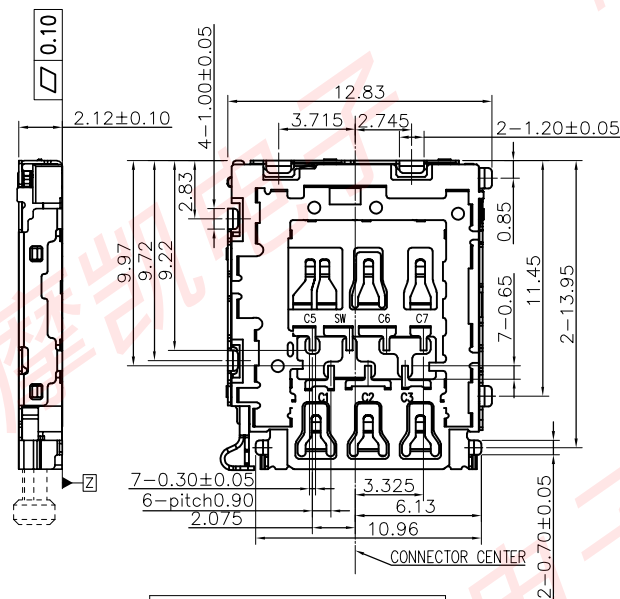


* 所有原料材质,生产制程,电镀必须符合HF要求



NOTE:

1. Material:
1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
1-2 Contact: Phosphor Bronze (C5210R-H, T=0.10±0.01mm)
1-3 Cover: SUS301-H T=0.15±0.03mm
2. Plating:
2-1 Contact terminal:
Contact area: Gold 1u" Min.
Solder area: Gold 0.8u" Min.
Underplating: Ni overall 50U" Min.
2-2 Cover:
Underplating: Ni overall 30U" Min.
Solder area: Gold 0.8u" Min.
3. Specification:
3-1. Current Rating :0.5A max.
3-2. Contact Resistance: 50 mOhms max
3-3. Insulation Resistance: 1000 MOhms min./500VDC
3-4. Dielectric Withstanding Voltage: 500 V AC/1minute
3-5. Operating Temperature: -25°C to +85°C
3-6. Mating Cycles: 5000 Insertions
4. Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
5. Part Must Comply Taisol HF WD-3-I-091 Specification.
6. Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

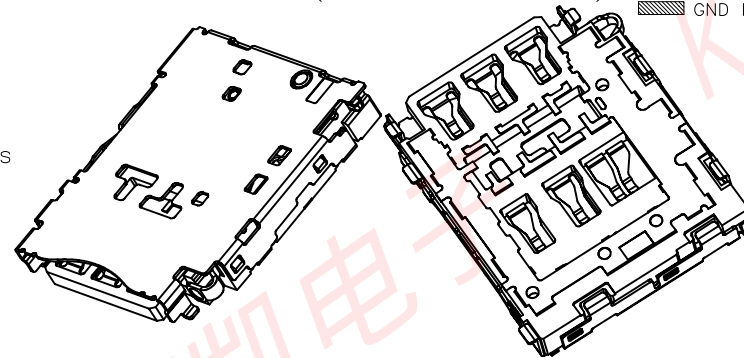
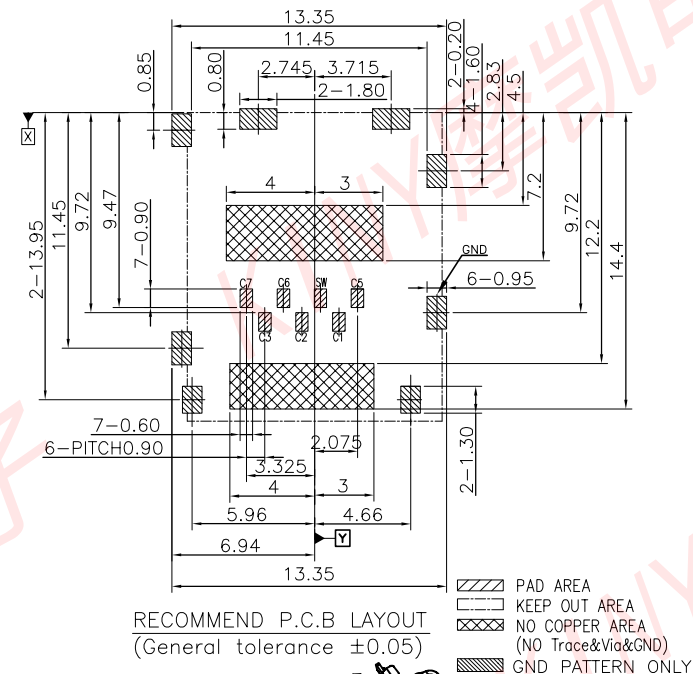


COMPOSITION OF DETECTION

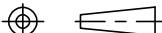
CARD DETECT(SW)
C5 ○ — ○ — SW
CARD DETECTION/SWITCH
CARD INSTALLATION:ON
NON CARD:OFF

SIM Card Pin Assignments

	NANO	SIM	CARD
	C1		Vcc
	C2		RST
	C3		CLK
	C5		GND
	SW		CD/SW
	C6		Vpp
	C7		DATA



B	ECN20181119001	修改参数 $\triangle$	janyz	2018.11.19
A	-----	NEW RELEASE	ping	2017.03.10
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

KINYO		东莞市摩凯电子有限公司			
DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2°		PRODUCT NAME : NANO SIM H2.15 CARD CONN(SMT)		DRAWING: Janyz	DATE: 2018.11.19
		PRODUCT NO. : NS215-T1131-01		CHECK: Alex	DATE: 2018.11.19
		DRAWING NO. : D-NS215-T1131-01		APPROVED: Alex	DATE: 2018.11.19
				SCALE: 1:1	DWG ID: C D